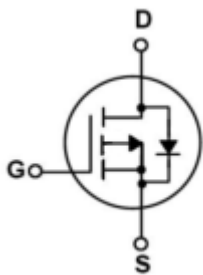


/ Descriptions

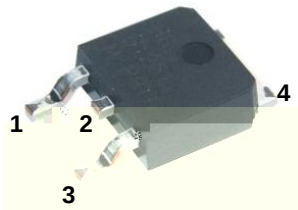
/ Features

/ Applications

/ Equivalent Circuit



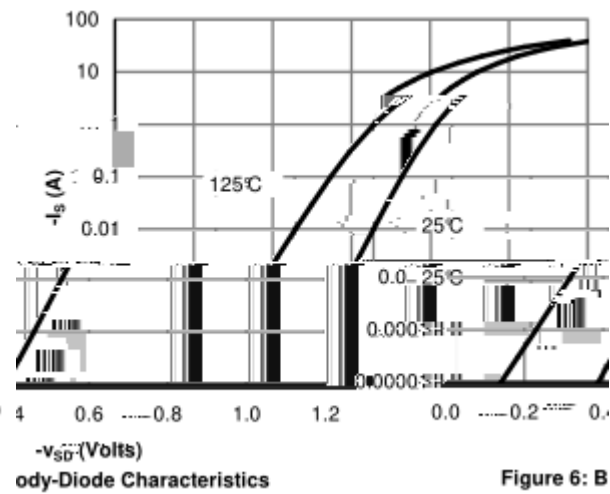
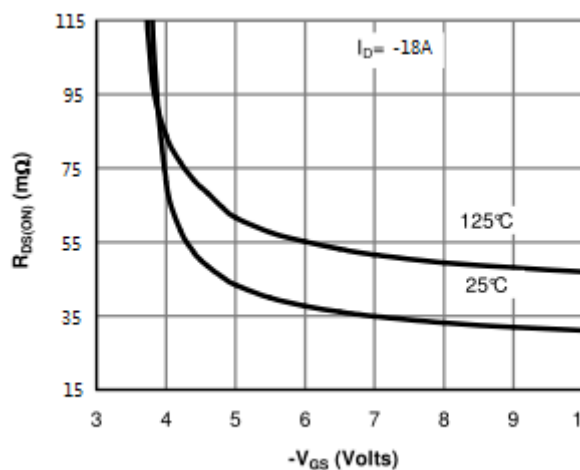
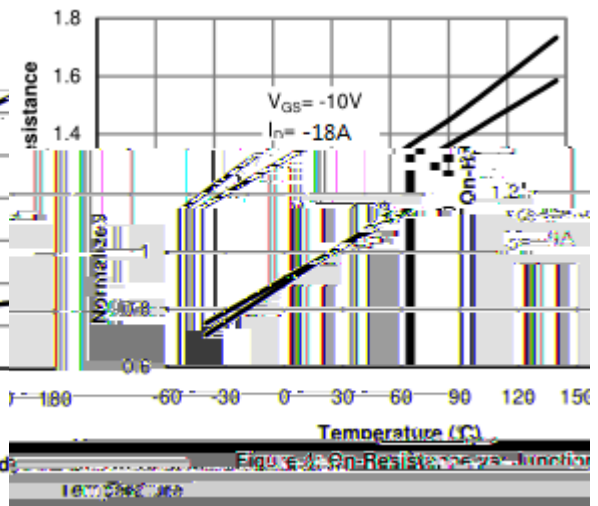
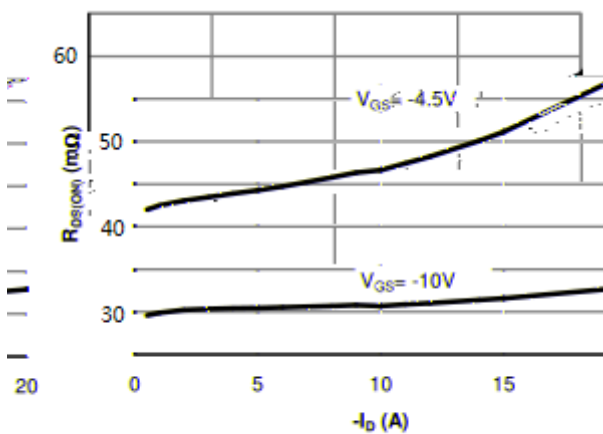
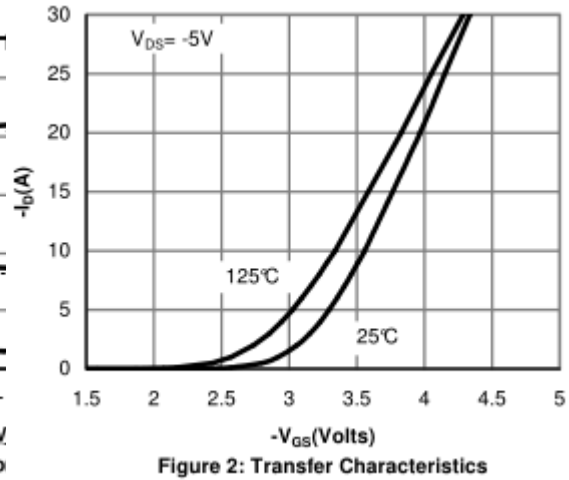
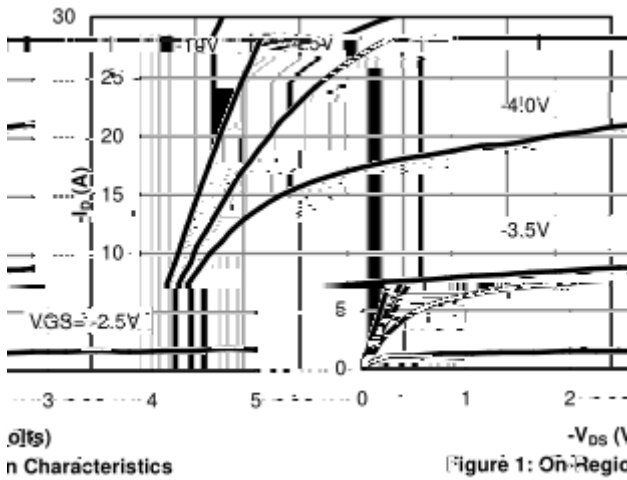
/ Pinning



/ h_{FE} Classifications & Marking

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/ Electrical Characteristic Curve



/ Electrical Characteristic Curve

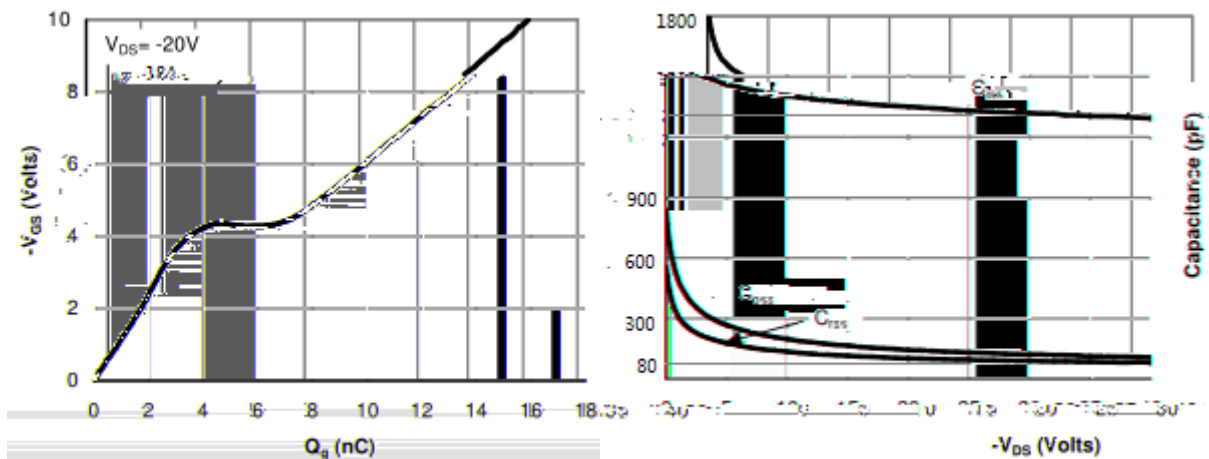


Figure 8: Capacitance Characteristics

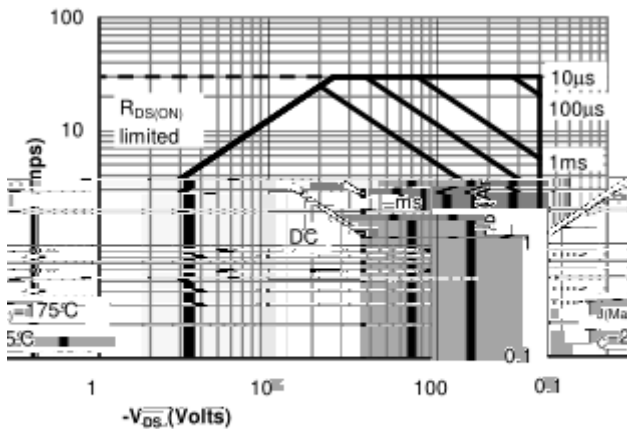


Figure 9: Maximum Forward Biased Safe Operating Area

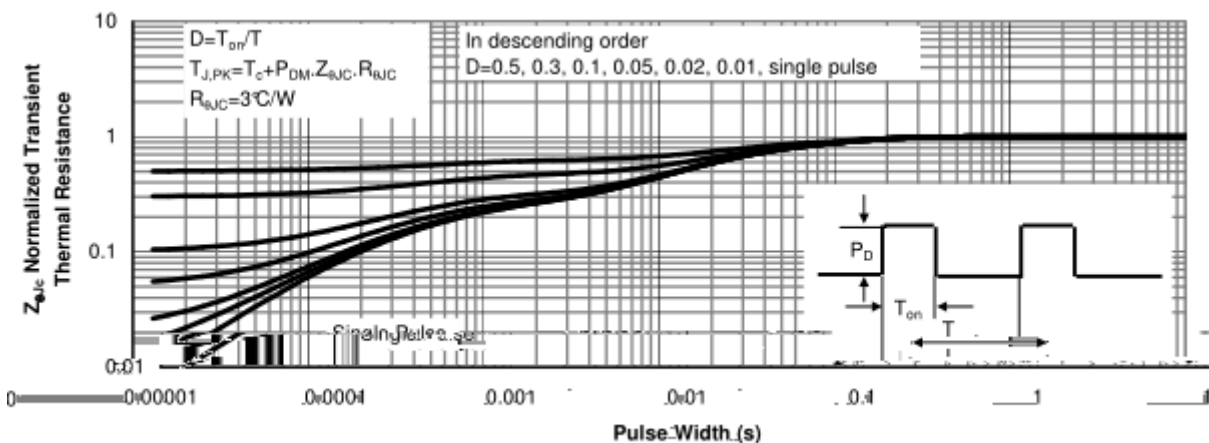
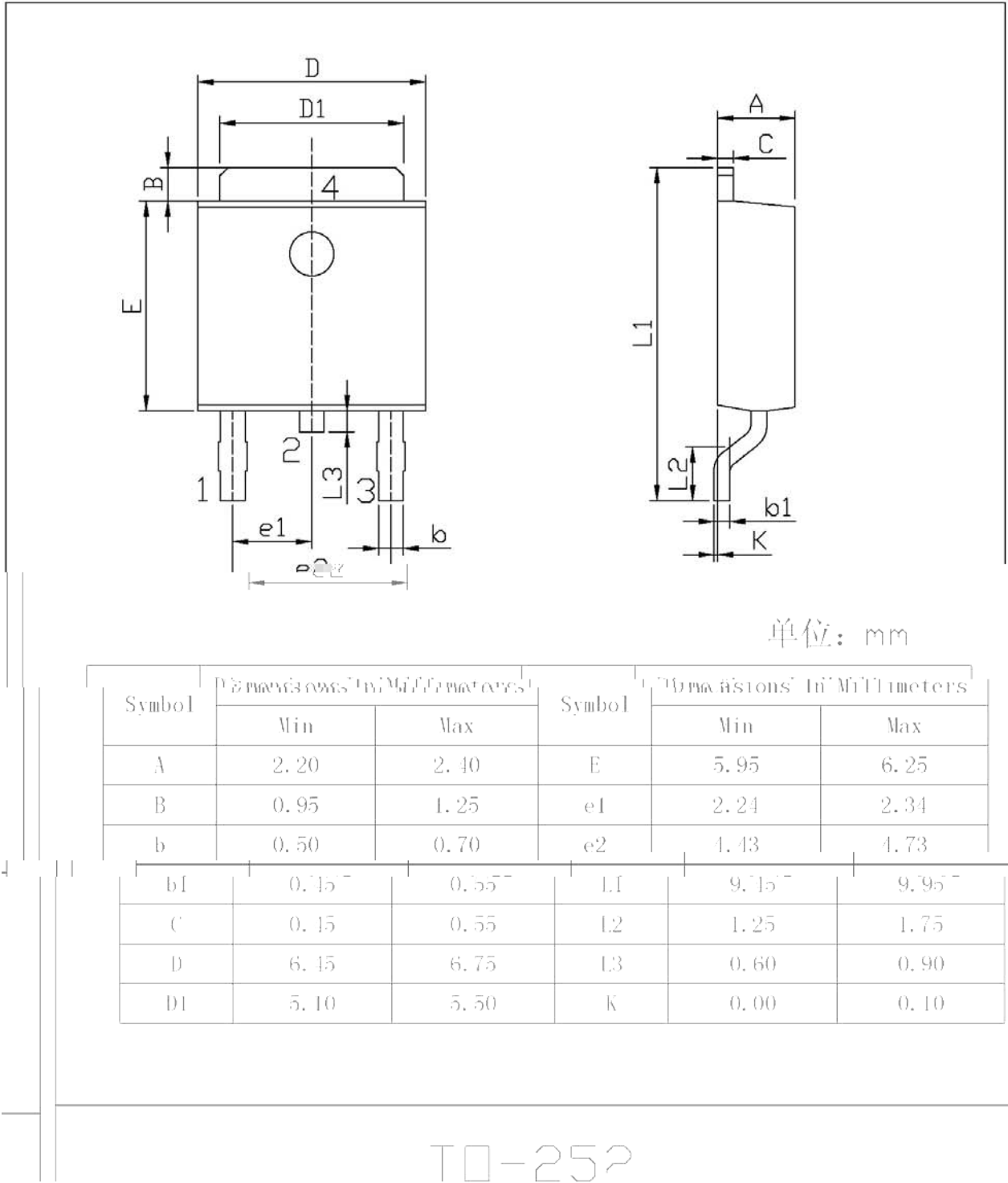
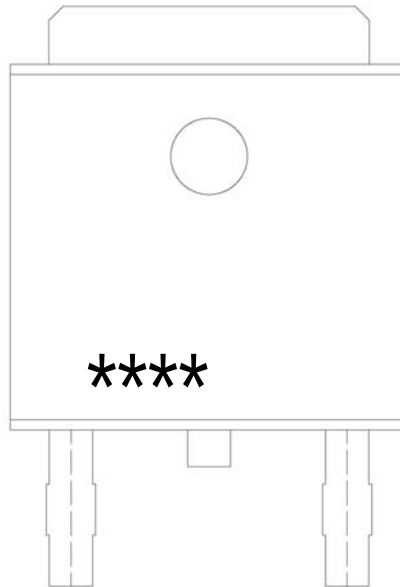


Figure 11: Normalized Maximum Transient Thermal Impedance

/ Package Dimensions

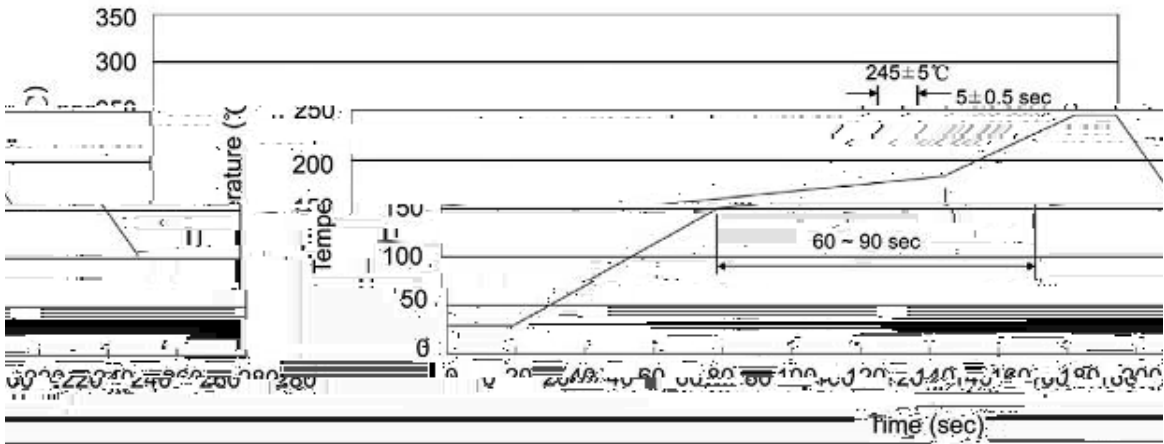


/ Marking Instructions



20P04

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ±

/ Packaging SPEC.

	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
TO-252	2,500	2	5,000	5	25,000	13" ×16	360×360×50	385×257×392

	Units/Tube /	Tubes/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Tube	Inner Box	Outer Box
TO-251/252	75	48	3,600	5	18,000	526×20.5×5.25	555×164×50	575×290×180

/ Notices